

Title (en)

SILICONE-EPOXY RESIN COMPOSITION AND CONDUCTIVE ADHESIVE PREPARED THEREFROM

Publication

**EP 0388473 A4 19920304 (EN)**

Application

**EP 89909855 A 19890901**

Priority

- JP 22155588 A 19880902
- JP 30652288 A 19881202

Abstract (en)

[origin: WO9002768A1] A silicone-epoxy resin composition of this invention comprises a silicone-epoxy resin of general formula (I) and a curing agent. It has an excellent compatibility with an epoxy resin or curing agent and a high curing rate and, when cured, offers well-balanced flexibility, humidity resistance and heat resistance. Hence, it is effective for the bonding and sealing of electric or electronic components requiring a low stress. For example, a conductive adhesive prepared by adding a conductive filler to this composition can exhibit an excellent performance in the bonding of large-sized ICs or LSIs or in assembling quartz oscillators.

IPC 1-7

**C08G 59/30**; **C09J 3/16**

IPC 8 full level

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Citation (search report)

- [X] BE 742710 A 19700605
- [X] DE 1251034 B
- [XP] EP 0319472 A2 19890607 - CIBA GEIGY AG [CH]
- [A] WORLD PATENTS INDEX LATEST Derwent Publications Ltd., London, GB; AN 85-015747 & JP-A-59 212 250 (MITSUBISHI ELECTRIC) 1 February 1984
- See references of WO 9002768A1

Cited by

US5227093A; EP0816461A3

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